





#### SECONDARY SIDE SYNCHRONOUS RECTIFICATION CONTROLLER

### **Description**

APR343 is a secondary side MOSFET driver for synchronous rectification in DCM operation, which integrates the output voltage detection function for primary side control system.

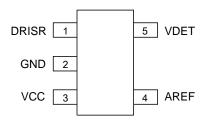
The synchronous rectification can effectively reduce the secondary side rectifier power dissipation and provide high performance solution. By sensing MOSFET drain-to-source voltage, APR343 can output ideal drive signal with less external components. It can provide high performance solution for 5V output voltage application.

Same as AP4341, APR343 detects the output voltage and provides a periodical signal when the output voltage is lower than a certain threshold. By fast response to secondary side voltage, APR343 can effectively improve the transient performance of primary side control system.

The APR343 is available in SOT25 package.

### Pin Assignments

#### (Top View)



SOT25

### **Features**

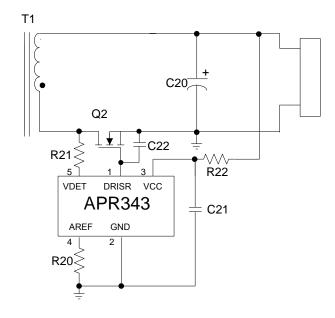
Notes:

- Synchronous Rectification for DCM Operation Flyback
- Eliminate Resonant Ring Interference
- Fast Detector of Supply Voltage
- Fewest External Components
- Totally Lead-free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
  - 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  - See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Applications

- Adapters/Chargers for Cell/Cordless Phones, ADSL Modems, MP3 and Other Portable Apparatus
- Standby and Auxiliary Power Supplies

## **Typical Applications Circuit**

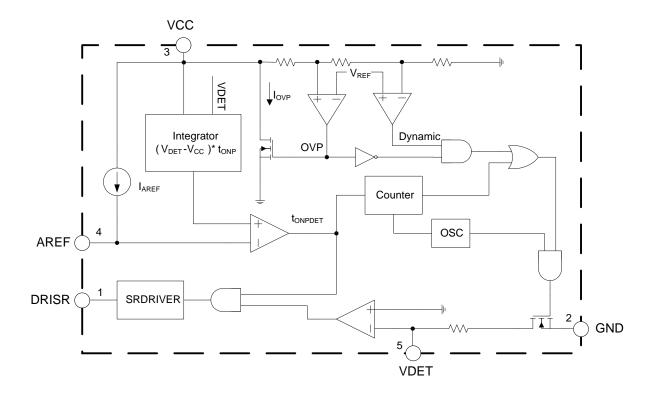




# **Pin Descriptions**

Pin Number	Pin Name	Function		
1	DRISR	Synchronous rectification MOSFET Gate drive		
2	GND	Ground		
3	VCC	Power supply, connected with system output		
4	l AREF	Program a voltage reference with a resistor from AREF to GND, to enable synchronous rectification MOSFET drive signal		
5	VDET	Synchronous rectification sense input and dynamic function output, connected with secondary winding		

# **Functional Block Diagram**





**APR343** 

# **Absolute Maximum Ratings** (Note 4)

Symbol	Parameter	Rating	Unit
V <sub>CC</sub>	Supply Voltage	-0.3 to 7.5	V
V <sub>DET</sub>	Voltage at VDET Pin	-2 to 50	V
Varef, Vdrisr	Voltage at AREF, DRISR Pin	-0.3 to 6	V
-	Output Current at VDET	Internally limited	А
P <sub>D</sub>	Power Dissipation at T <sub>A</sub> = +25°C	0.6	W
TJ	Operating Junction Temperature	+150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
_	Lead Temperature (Soldering, 10 sec)	+300	°C
θ <sub>JA</sub>	Thermal Resistance (Junction to Ambient)	197	°C/W
θις	Thermal Resistance (Junction to Case)	76	°C/W

Note 4: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

# **Recommended Operating Conditions**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	0	6	V
TA	Ambient Temperature	-40	+85	°C





**APR343** 

## Electrical Characteristics (@V<sub>CC</sub> = 5V, T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameters	Conditions	Min	Тур	Max	Unit	
Supply Voltage (	VCC Pin )						
ISTARTUP	Startup Current	Vcc = Vstartup-0.1V	-	100	150	μA	
I <sub>OP</sub>	Operating Current	VDET pin floating V <sub>CC</sub> = V <sub>TRIGGER</sub> +20mV	40	100	150	μA	
V <sub>STARTUP</sub>	Startup Voltage	_	2.6	3.1	3.4	V	
_	UVLO	-	2.3	2.8	3.1	V	
Dynamic Output	Section/Oscillator Section						
V <sub>TRIGGER</sub>	Internal Trigger Voltage	_	5.25	5.3	5.35	V	
-	Duty Cycle	-	4	8	12	%	
tosc	Oscillation Period	V <sub>CC</sub> = 5V	18	30	37.5	μs	
I <sub>TRIGGER</sub>	Internal Trigger Current	$V_{CC} = V_{TRIGGER}$ , VCC/VDET pin is separately connected to a $20\Omega$ resistor	30	_	42	mA	
t <sub>DIS</sub>	Minimum Period	_	18	30	37.5	ms	
V <sub>DIS</sub>	Discharge Voltage	_	5.28	5.44	5.52	V	
I <sub>DIS</sub>	Discharge Current	$V_{CC} = V_{DIS} + 0.1V$	1.5	3	4.5	mA	
V <sub>DIS</sub> -V <sub>TRIGGER</sub>	Trigger Discharger Gap	_	30	110	_	mV	
V <sub>OVP</sub>	Overshoot Voltage for Discharge	-	5.8	5.9	6.0	V	
I <sub>OVP</sub>	Overshoot Current for Discharge	$V_{CC} = V_{OVP} + 0.1V$ , VCC pin is connected to a $20\Omega$ resistor	40	_	100	mA	
Synchronous Rec	ctification Detection and Drive						
$V_{THON}$	Gate Turn On Threshold	_	0	_	1	V	
$V_{THOFF}$	Gate Turn Off Threshold	_	-20	-12.5	-5	mV	
$t_{DON}$	Turn On Delay Time	From V <sub>THON</sub> to V <sub>DRISR</sub> = 1V	_	70	130	ns	
t <sub>DOFF</sub>	Turn Off Propagation Delay Time	From V <sub>THOFF</sub> to V <sub>DRISR</sub> = 3V	_	100	150	ns	
t <sub>RG</sub>	Turn On Rising Time	From 1V to 3V, C <sub>L</sub> = 4.7nF	_	50	100	ns	
t <sub>FG</sub>	Turn Off Falling Time	From 3V to 1V, C <sub>L</sub> = 4.7nF	_	50	100	ns	
t <sub>LEB_S</sub>		$(V_{DET}-V_{CC})*t_{ONP} = 25V\mu s$	0.9	1.8	2.7		
t <sub>LEB_L</sub>	Minimum On Time	(V <sub>DET</sub> -V <sub>CC</sub> )*t <sub>ONP</sub> = 50Vµs	_	_	6.5	μs	
V <sub>DRISR_HIGH</sub>	Drive Output Voltage	V <sub>CC</sub> = 5V	3.7	_	-	V	
$V_{S\_MIN}$	Synchronous Rectification (SR) Minimum Operating Voltage (Note 5)	-	-	-	4.5	V	
t <sub>OVP_LAST</sub>	Added OVP Discharge Time	_	_	2.0	_	ms	
Kqs	(Note 6)	(V <sub>DET</sub> -V <sub>CC</sub> )*t <sub>ONP</sub> = 25Vµs	0.325	_	0.625	mA*µs	

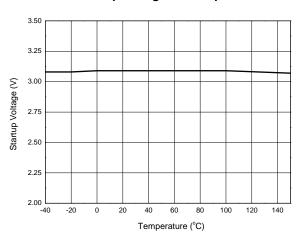
Notes: 5. This item specifies the minimum SR operating voltage of  $V_{IN\_DC}$ ,  $V_{IN\_DC} \ge N_{PS} * V_{S\_MIN}$ .

6. This item is used to specify the value of  $R_{\mathsf{AREF}}$ .

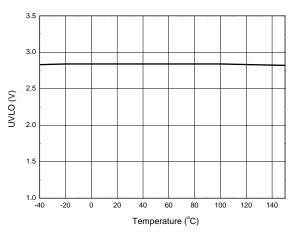


### **Performance Characteristics**

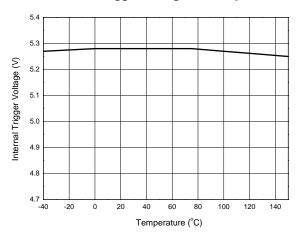
### Startup Voltage vs. Temperature



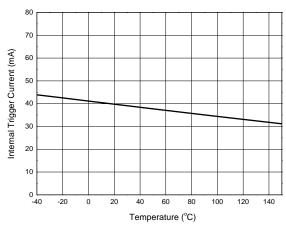
### **UVLO vs. Temperature**



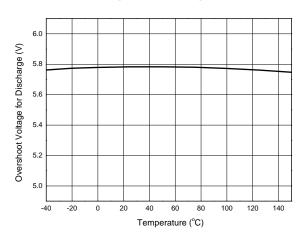
### Internal Trigger Voltage vs. Temperature



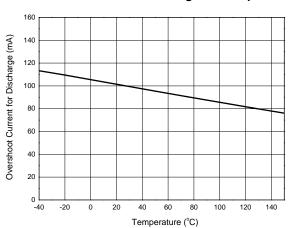
### Internal Trigger Current vs. Temperature



### Overshoot Voltage for Discharge vs. Temperature



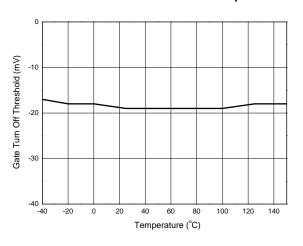
### **Overshoot Current for Discharge vs. Temperature**



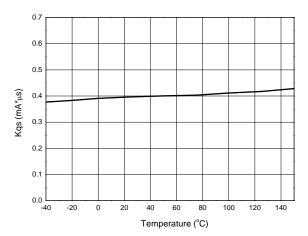


# **Performance Characteristics (Cont.)**

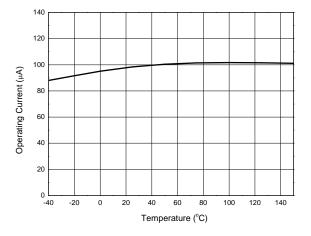
### Gate Turn Off Threshold vs. Temperature



### Kqs (See Note 6) vs. Temperature



### **Operating Current vs. Temperature**





# **Output Voltage Detection Function Description**

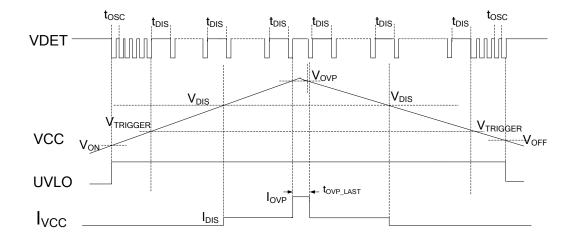


Figure 1. Typical Waveforms 1 of APR343

When  $V_{CC}$  is beyond power-on voltage  $(V_{ON})$ , the APR343 starts up. The VDET pin asserts a periodical pulse and the oscillation period is  $t_{OSC}$ . When  $V_{CC}$  is beyond the trigger voltage  $(V_{TRIGGER})$ , the periodical pulse at VDET pin is discontinued. When  $V_{CC}$  is beyond the discharge voltage  $(V_{DIS})$ , the discharge circuit will be enabled, and a 3mA current  $(I_{DIS})$  will flow into VCC pin. When  $V_{CC}$  is higher than the overshoot voltage  $(V_{OVP})$ , the APR343 will enable a discharge circuit, the discharge current  $(I_{OVP})$  will last  $t_{OVP\_LAST}$  time. After the  $t_{OVP\_LAST}$  time, APR343 will stop the discharge current and detect VCC voltage again. If  $V_{CC}$  is still higher than  $V_{OVP}$ , the  $t_{OVP\_LAST}$  time discharge current will be enabled again. Once the OVP discharge current is asserted, the periodical pulse at VDET pin will be disabled.

When the V<sub>CC</sub> is below the power-off voltage (V<sub>OFF</sub>), the APR343 will be shut down.

# **MOSFET Driver Operation Description**

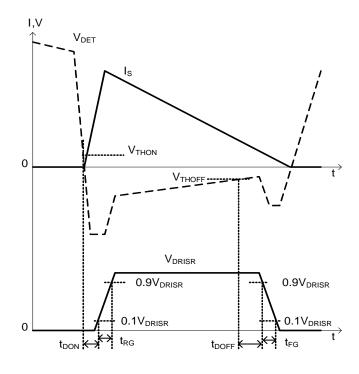


Figure 2. Typical Waveforms 2 of APR343



### **MOSFET Driver Operation Description (Cont.)**

The operation of the SR is described with timing diagram shown in Figure 2. APR343 monitors the MOSFET drain-source voltage. When the drain voltage is lower than the turn-on threshold voltage  $V_{THON}$ , the IC outputs a positive drive voltage after a turn-on delay time ( $t_{DON}$ ). The MOSFET will turn on and the current will transfer from the body diode into the MOSFET's channel.

In the process of drain current decreasing linearly toward zero, the drain-source voltage rises synchronically. When it rises over the turn off threshold voltage  $V_{THOFF}$ , APR343 pulls the drive signal down after a turn off delay ( $t_{DOFF}$ ).

#### **Minimum On Time**

When the controlled MOSFET gate is turned on, some ringing noise is generated. The minimum on-time timer blanks the  $V_{THOFF}$  comparator, keeping the controlled MOSFET on for at least the minimum on time. If  $V_{THOFF}$  falls below the threshold before minimum on time expires, the MOSFET will keep on until the end of the minimum on time.

The minimum on time is in direct proportion to the (V<sub>DET</sub>-V<sub>CC</sub>)\*t<sub>ONP</sub>. When (V<sub>DET</sub>-V<sub>CC</sub>)\*t<sub>ONP</sub>=5V\*5µs, the minimum on time is about 1.8µs.

#### The Value and Meaning of AREF Resistor

As to DCM operation Flyback converter, after secondary rectifier stops conduction the primary MOSFET Drain-to-source ringing waveform is resulted from the resonant of primary inductance and equivalent switch device output capacitance. This ringing waveform probably leads to Synchronous Rectifier error conduction. To avoid this fault happening, APR343 has a special function design by means of volt-second product detecting. From the sensed voltage of VDET pin to see, the volt-second product of voltage above  $V_{CC}$  at primary switch on time is much higher than the volt-second product of each cycle ringing voltage above  $V_{CC}$ . Therefore, before every time Synchronous Rectifier turning on, APR343 judges if the detected volt-second product of VDET voltage above  $V_{CC}$  is higher than a threshold and then turn on synchronous Rectifier. The purpose of AREF resistor is to determine the volt-second product threshold. APR343 has a parameter, Kqs, which converts  $R_{AREF}$  value to volt-second product.

$$Area2 = R_{AREF} * Kqs$$

In general, Area1 and Area3 value depend on system design and always are fixed after system design frozen. As to BCD PSR design, the Area1 value changes with primary peak current value and Area3 value generally keeps constant at all of conditions. So the AREF resistor design should consider the worst case, the minimum primary peak current condition. Since of system design parameter distribution, Area1 and Area3 have moderate tolerance. So Area2 should be designed between the middle of Area1 and Area3 to keep enough design margin.

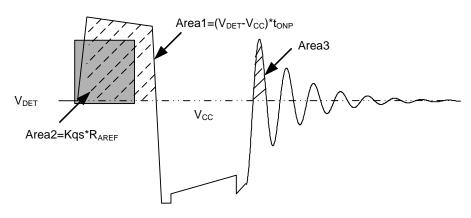


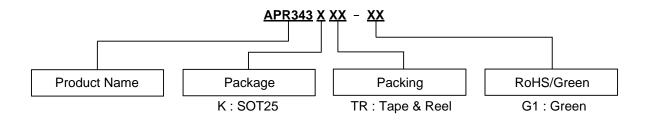
Figure 3. AREF Function

#### SR Minimum Operating Voltage

APR343 sets a minimum SR operating voltage by comparing the difference between  $V_{DET}$  and output voltage ( $V_{CC}$ ). The value of  $V_{DET}$ – $V_{CC}$  must be higher than its internal reference, then APR343 will begin to integrate the area of  $(V_{DET}$ – $V_{CC})$ \* $t_{ONP}$ . If not, the area integrating will not begin and the SR driver will be disabled.



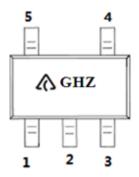
# **Ordering Information**



Package	Temperature Range	Part Number	Marking ID	Packing	
SOT25	-40°C to +85°C	APR343KTR-G1	GHZ	3000/Tape & Reel	

# **Marking Information**

### (Top View)

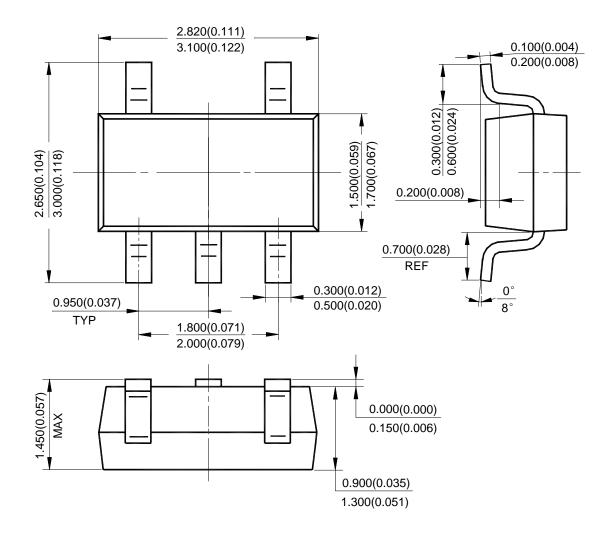


: Logo GHZ: Marking ID



## Package Outline Dimensions (All dimensions in mm(inch).)

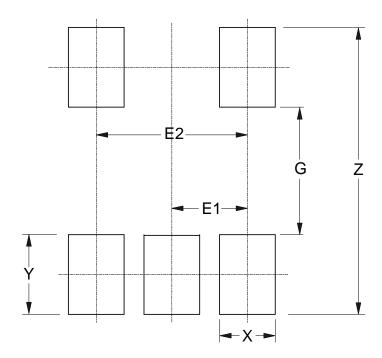
### (1) Package Type: SOT25





# **Suggested Pad Layout**

### (1) Package Type: SOT25



Dimensions	Z	G	X	Υ	E1	E2
Dimensions	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	3.600/0.142	1.600/0.063	0.700/0.028	1.000/0.039	0.950/0.037	1.900/0.075



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